



GP
ELECTRONICS

GPM065P02UNA
20V P-Channel MOSFET

Product Summary

$V_{(BR)DSS}$	$R_{DS(on)TYP}$	I_D
-20V	6.5mΩ@-4.5V	-40A
	8.8mΩ@-2.5V	

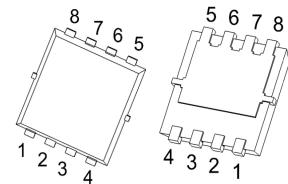
Feature

- Trench Technology Power MOSFET
- Low $R_{DS(ON)}$
- Low Gate Charge
- Low Gate Resistance
- 100% UIS Tested
- 100% ΔV_{DS} Tested

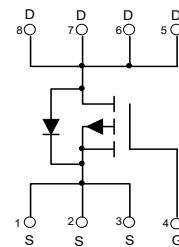
Application

- Power Switching Application

PDFN3.3×3.3-8L



Schematic diagram



MARKING:



M065P02U = Device Code

XX = Date Code

Solid Dot = Green Indicator

ABSOLUTE MAXIMUM RATINGS ($T_A = 25^\circ\text{C}$ unless otherwise noted)

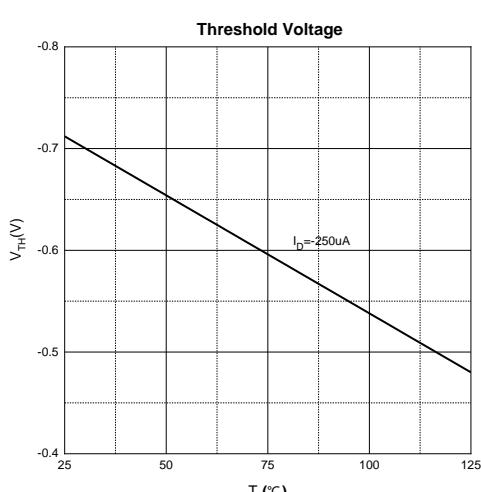
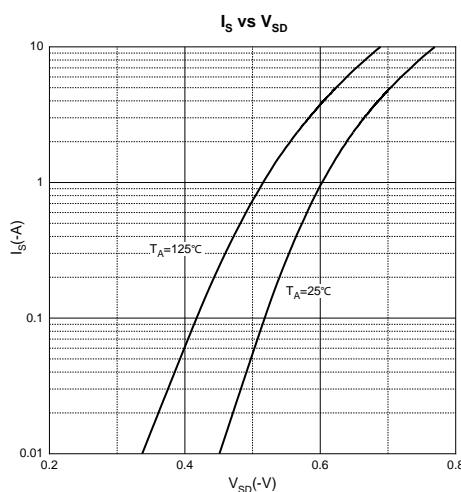
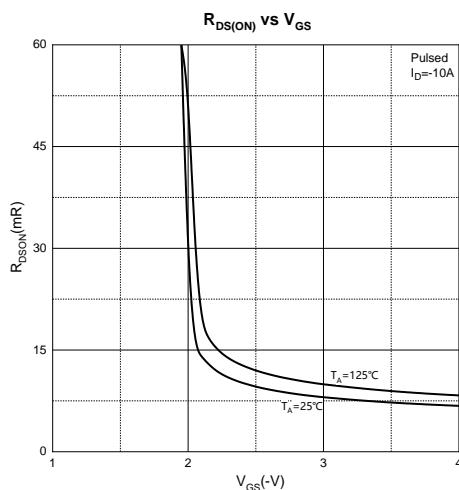
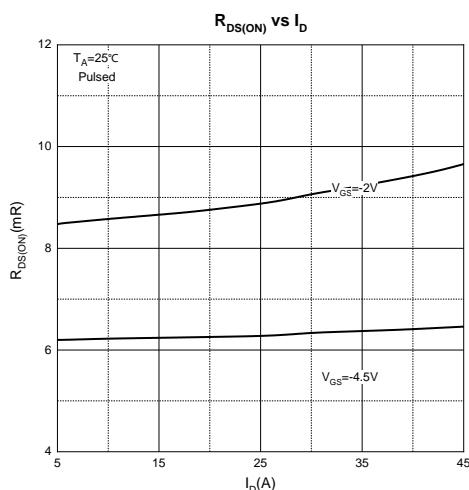
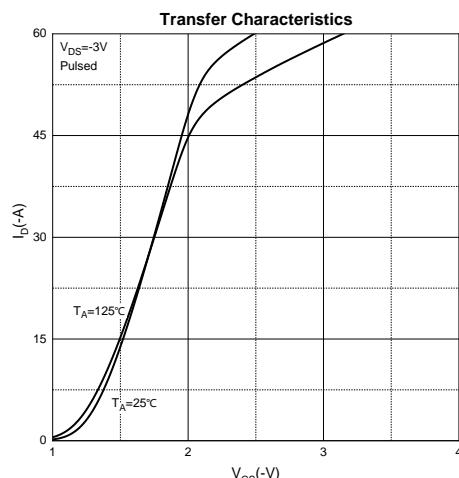
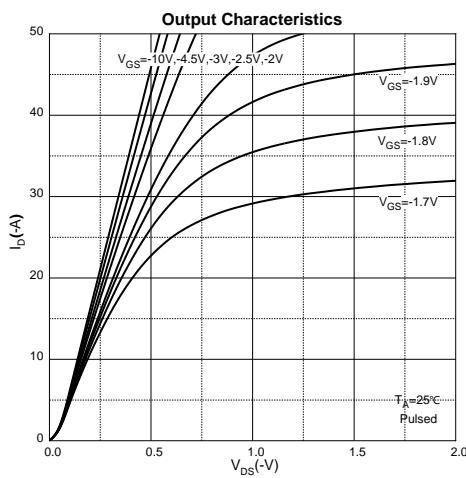
Parameter	Symbol	Value	Unit
Drain - Source Voltage	V_{DS}	-20	V
Gate - Source Voltage	V_{GS}	± 12	V
Continuous Drain Current ¹	I_D	-40	A
	I_D	-26	A
Pulsed Drain Current ²	I_{DM}	-160	A
Single Pulsed Avalanche Current ³	I_{AS}	-22	A
Single Pulsed Avalanche Energy ³	E_{AS}	121	mJ
Power Dissipation ⁵	P_D	39	W
Thermal Resistance from Junction to Ambient ⁶	$R_{\theta JA}$	38	°C/W
Thermal Resistance from Junction to Case	$R_{\theta JC}$	3.2	°C/W
Junction Temperature	T_J	150	°C
Storage Temperature	T_{STG}	-55~+150	°C

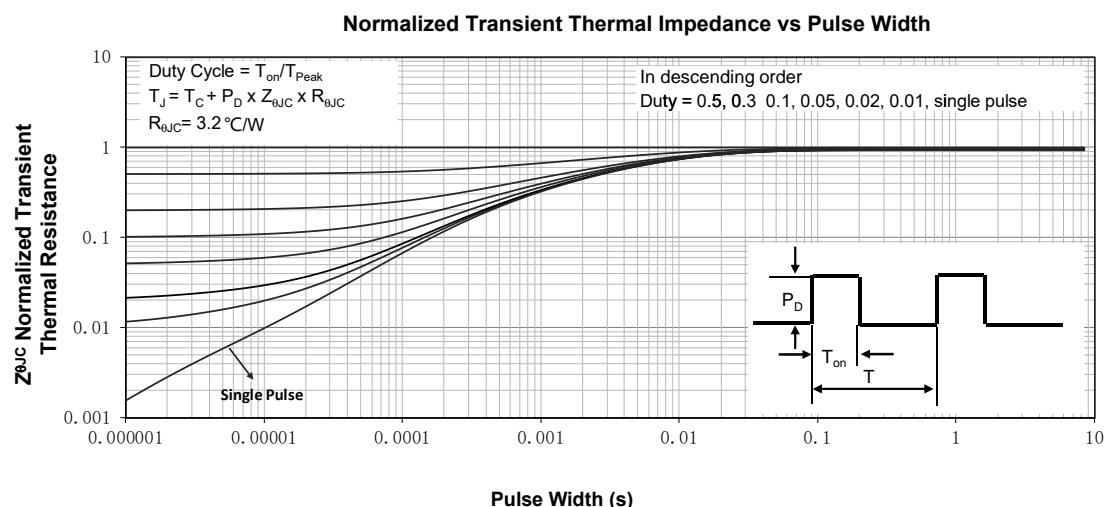
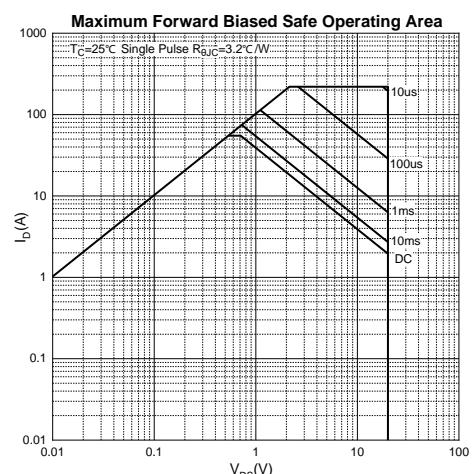
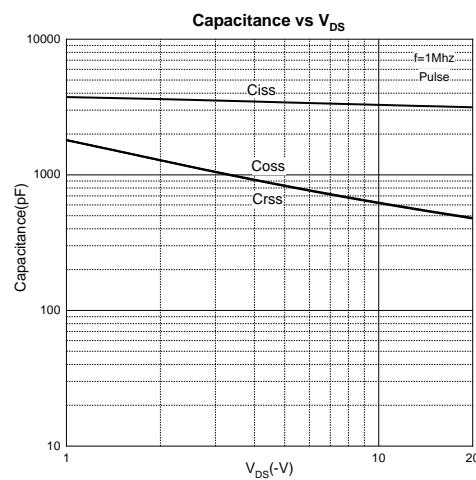
MOSFET ELECTRICAL CHARACTERISTICS ($T_J = 25^\circ\text{C}$ unless otherwise noted)

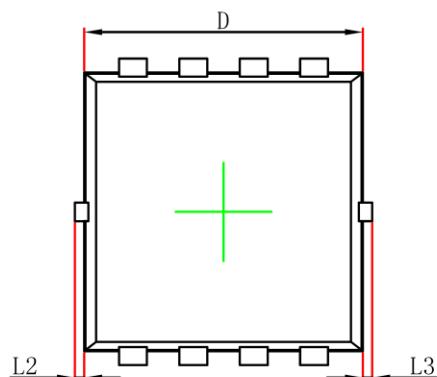
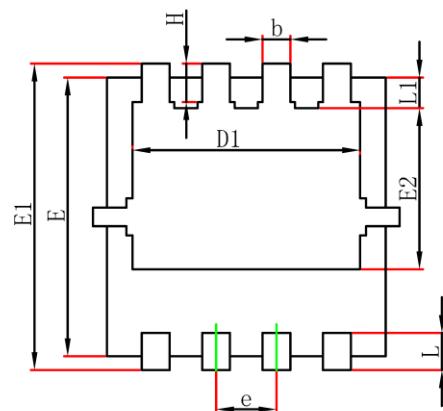
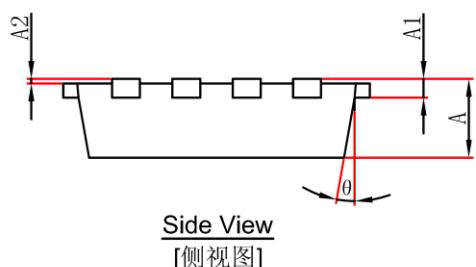
Parameter	Symbol	Test Condition	Min	Type	Max	Unit
Off Characteristics						
Drain - Source Breakdown Voltage	$V_{(\text{BR})\text{DSS}}$	$V_{GS} = 0V, I_D = -250\mu\text{A}$	-20			V
Zero Gate Voltage Drain Current	I_{DSS}	$V_{DS} = -20V, V_{GS} = 0V$			-1	μA
Gate - Body Leakage Current	I_{GSS}	$V_{GS} = \pm 12V, V_{DS} = 0V$			± 100	nA
On Characteristics⁴						
Gate Threshold Voltage	$V_{GS(\text{th})}$	$V_{DS} = V_{GS}, I_D = -250\mu\text{A}$	-0.4	-0.7	-1.0	V
Drain-source On-resistance	$R_{DS(\text{on})}$	$V_{GS} = -4.5V, I_D = -10\text{A}$		6.5	9	$\text{m}\Omega$
		$V_{GS} = -2.5V, I_D = -10\text{A}$		8.8	13	
Dynamic Characteristics						
Input Capacitance	C_{iss}	$V_{DS} = -10V, V_{GS} = 0V, f = 0.1\text{MHz}$		3265		pF
Output Capacitance	C_{oss}			622		
Reverse Transfer Capacitance	C_{rss}			595		
Gate Resistance	R_g	$V_{DS} = 0V, V_{GS} = 0V, f = 1\text{MHz}$		4.8		Ω
Switching Characteristics						
Total Gate Charge	Q_g	$V_{DS} = -17V, V_{GS} = -4.5V, I_D = -10\text{A}$		47.5		nC
Gate-source Charge	Q_{gs}			4.4		
Gate-drain Charge	Q_{gd}			18.7		
Turn-on Delay Time	$t_{d(\text{on})}$	$V_{DD} = -10V, V_{GS} = -4.5V, I_D = -15\text{A}, R_G = 3\Omega$		15		ns
Turn-on Rise Time	t_r			20		
Turn-off Delay Time	$t_{d(\text{off})}$			90		
Turn-off Fall Time	t_f			160		
Source - Drain Diode Characteristics						
Diode Forward Voltage ⁴	V_{SD}	$V_{GS} = 0V, I_s = -10\text{A}$			-1.2	V

Notes :

- 1.The maximum current rating is limited by package.And device mounted on a large heatsink
- 2.Pulse Test : Pulse Width $\leq 10\mu\text{s}$, duty cycle $\leq 1\%$.
- 3.E_{AS} condition: $V_{DD} = -15V, V_{GS} = -10V, L = 0.5\text{mH}, R_G = 25\Omega$ Starting $T_J = 25^\circ\text{C}$.
- 4.Pulse Test : Pulse Width $\leq 300\mu\text{s}$, duty cycle $\leq 2\%$.
- 5.The power dissipation P_D is limited by $T_{J(\text{MAX})} = 150^\circ\text{C}$.And device mounted on a large heatsink
- 6.Device mounted on 1in² FR-4 board with 2oz. Copper, in a still air environment with $T_A = 25^\circ\text{C}$.

Typical Characteristics




PDFN3.3x3.3-8L Package Information

Top View
[顶视图]

Bottom View
[背视图]

Side View
[侧视图]

Symbol	Dimensions In Millimeters		Dimensions In Inches	
	Min.	Max.	Min.	Max.
A	0.700	0.900	0.028	0.035
A1	0.152REF		0.006REF	
A2	0.000	0.050	0.000	0.002
D	2.900	3.200	0.114	0.126
D1	2.300	2.600	0.091	0.102
E	2.900	3.200	0.114	0.126
E1	3.150	3.450	0.124	0.136
E2	1.535	1.935	0.060	0.076
b	0.200	0.400	0.008	0.016
e	0.550	0.750	0.022	0.030
L	0.300	0.500	0.012	0.020
L1	0.180	0.480	0.007	0.019
L2	0.000	0.100	0.000	0.004
L3	0.000	0.100	0.000	0.004
H	0.315	0.515	0.012	0.020
θ	0°	12°	0°	12°